Product/Process Change Notice - PCN 13_0246 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title:	Assembly and Test Transfer of Select 3x3, 5x5 and 7x7 mm LFCSP Pre-plated Leadframe Products to STATS ChipPAC China
Publication Date:	07-Nov-2013
Effectivity Date:	18-May-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to subcontractor STATS ChipPAC China for the assembly and test manufacturing of ADI 3x3, 5x5 and 7x7 mm LFCSP pre-plated leadframe products. The package outline dimensions and BOM of each product will be maintained.

Reason For Change

ADI is transferring to STATS ChipPAC China due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary. Test correlation and validation will also be performed.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_13_0246_Rev_-_Reliability Qualification Plan.pdf

Attachment 2: Type: Test Correlation Plan

ADI_PCN_13_0246_Rev_-_Test Qualification Plan.pptx

Attachment 3: Type: Detailed Change Description

ADI_PCN_13_0246_Rev_-_BOM.pptx

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (7)

ADA4930-1 / ADA4930-1SCPZ-EPR2	ADA4930-1 / ADA4930-1SCPZ-EPR7	ADA4930-1 / ADA4930-1SCPZ-EPRL	ADF7020 / AD45203Z-RL	ADF7023 / AD57/005Z-0RL
ADF7023 / ADF7023BCPZ	ADF7023 / ADF7023BCPZ-RL			

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	07-Nov-2013	18-May-2014	Initial Release

Reliability Qualification Plan for LFCSP Package in NiPdAu Pre-plated Leadframe at STATS ChipPAC China (SCC)

QUALIFICATION PLAN

Test	Conditions	Sample Size	Expected Completion Date
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	April 2014
Low Temperature Storage (LTS)	JEDEC *JESD22-A119*	**3 x 77**	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	April 2014

*Preconditioned per JEDEC/IPC J-STD-020